1. An electrical contact for a microelectronic device comprising:

a first contact pad; and

a resinous member having conductive particles, said member extending upwardly from said first contact pad.

2. The contact of claim 1 wherein said member is in the form of an upstanding annular shape.

3. The contact of claim 2 wherein said annular shape tapers as it extends upwardly.

4. The contact of claim 3 including metallic flakes dispersed through a polymeric resin.

5. The contact of claim 4 wherein said resin is thermoplastic.

6. An electrical connector for a microelectronic device comprising:

a first contact pad;

a resinous member having conductive particles dispersed through said member and having upper and lower ends; and

a second contact pad connected to the upper end of said member, said first contact pad connected to the lower end of said member.

7. The connector of claim 6 wherein said member is formed of a thermoplastic resin having dispersed metallic particles.

8. The connector of claim 7 wherein said thermoplastic resin has been connected to said first and second pads by curing said resin above its glassy transition temperature.

9. The connector of claim 6 wherein said member is of an annular configuration..

10. The connector of claim 6 wherein said resinous member includes a resin having a thixotropic index of about 6 or greater.

11. The connector of claim 10 wherein said resinous member has a viscosity of approximately 200,000 centipoise.

12. The connector of claim 10 wherein said conductive particles are silver flakes.

13. The connector of claim 12 wherein said silver flakes have a particle size of 1/4 to 1 mil.

14. The connector of claim 6 wherein said resinous member has a height of from about 3 to about 10 mil.

15. An electrical contact for a semiconductor device comprising an annular member formed of conductive particles in a resinous matrix, said member adapted to physically and electrically connect to conductive terminations.

16. A method of electrically contacting a surface comprising the steps of:

depositing an annular member formed of

conductive particles in a resinous matrix; and

physically connecting said member between a pair of conductive surfaces.

17. The method of claim 16 including the steps of forming a stencil with an annular opening therethrough and forcing a resinous material through said stencil opening to form said annular member.

18. The method of claim 17 including the step of causing the conductive particles to align with one another to form an electrical connection along a surface of said member.

19. The method of claim 18 including the steps of heating said member to its glassy transition temperature and causing said member to bond to a contact surface.

20. A method of making electrical contact comprising the steps of:

forming an upstanding conductive, annular member on a first contact surface;

contacting a second contact surface with said member; and

heating said member to bond said member to said second contact surface.

21. The method of claim 20 including the step of forming said member by depositing a resinous matrix having dispersed conductive particles.

22. The method of claim 20 including the step of using said member as a guide to center and align a conductive bump to be contacted by said member.

23. The method of claim 21 including the step of curing said member above its glassy transition temperature in contact with said second contact surface.

24. A stencil for forming a deposit for making an electrical contact comprising:

an annular opening formed in said stencil; and

at least one bridge element across said annular opening.

25. The stencil of claim 24 having a thickness of from about 3 to about 10 mils.

26. The stencil of claim 25 wherein said annular opening has a radial width of about 1 mil.

27. A method of forming a deposit in making semiconductor devices comprising the steps of:

forming at least one annular opening in a plate creating an inner member inward of said opening and an outer member outward of said opening; and

maintaining a physical connection between said inner and outer members.

28. The stencil of claim 27 having a thickness of from about 3 to about 10 mils.

29. The stencil of claim 28 wherein said annular opening has a radial width of about 1 mil.

30. A resinous electrically conductive material comprising:

a resinous body having an edge surface; and

a plurality of electrically conductive particles lapping one another along said edge surface so as to form an electrically conductive path along said edge surface.

31. The material of claim 30 wherein said body is formed of a thermoplastic polymer.

32. The material of claim 31 wherein said particles are metallic flakes.

33. The material of claim 30 including at least two edge surfaces to provide at least two separate conductive paths.